MF1SPLUSx0y1

Mainstream contactless smart card IC for fast and easy solution development

Rev. 3.2 — 21 February 2011
187032

Product short data sheet
PUBLIC

1. General description

Migrate classic contactless smart card systems to the next security level! MIFARE Plus brings benchmark security to mainstream contactless smart card applications. It is the only mainstream IC compatible with MIFARE Classic 1K (MF1ICS50) and MIFARE Classic 4K (MF1ICS70) which offers an upgrade path for existing infrastructures and services.

After the security upgrade, MIFARE Plus uses AES-128 (Advanced Encryption Standard) for authentication, data integrity and encryption. MIFARE Plus is based on open global standards for both air interface and cryptographic methods at the highest security level.

MIFARE Plus is available in two versions: MIFARE Plus S and MIFARE Plus X.

- The MIFARE Plus S (MF1SPLUSx0y1, described in this data sheet) is the standard version for straight forward migration of MIFARE Classic systems. It is configured to offer high data integrity.
- The MIFARE Plus X (MF1PLUSx0y1) offers more flexibility to optimize the command flow for speed and confidentiality. It offers a rich feature set including proximity checks against relay attacks.

2. Features and benefits

- 2 kB or 4 kB EEPROM
- Simple fixed memory structure compatible with MIFARE Classic 1K and MIFARE Classic 4K
- Memory structure identical to MIFARE Classic 4K (sectors, blocks)
- Access conditions freely configurable
- Supports ISO/IEC 14443 Type A[1] UIDs (4-byte UID, 4 Byte NUID, 7-byte UID), optional support of random IDs
- Multi-sector authentication, Multi-block read and write
- AES-128 used for authenticity and integrity
- Anti-tearing mechanism for writing AES keys
- Keys can be stored as MIFARE CRYPTO1 keys (2 × 48-bit per sector) and as AES keys (2 × 128-bit per sector)
- Basic support of virtual card concept
- Communication speed up to 848 kbit/s

1. ISO/IEC 14443-x used in this data sheet refers to ISO/IEC 14443 Type A.

- Number of single write operations: 200000 cycles (typical)
- Common Criteria Certification: EAL4+

3. Applications

- Public transportation
- Access management such as employee, school or campus cards
- Electronic toll collection
- Closed loop micro payment
- Car parking
- Internet cafés
- Loyalty programs

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
C_i	input capacitance	T_{amb} = 22 °C; f_i = 13.56 MHz; 2.8 V RMS	[1]	15.0	17.0	19.04	pF
f_i	input frequency			-	13.56	-	MHz
EEPROM characteristics							
t_{ret}	retention time	T_{amb} = 22 °C		10	-	-	year
$N_{endu(W)}$	write endurance	T_{amb} = 22 °C; excluding anti-tearing for AES keys or sector trailers in security level 3		100000	200000	-	cycle

[1] Measured with LCR meter.

5. Ordering information

Table 2. Ordering information

Type number	Package			
	Commercial Name	Name	Description	Version
MF1SPLUS8001DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format) see Ref. 3, 4 kB EEPROM, 7-byte UID	-
MF1SPLUS8011DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format) see Ref. 3, 4 kB EEPROM, 4-byte UID	-
MF1SPLUS8031DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format), 4K EEPROM, 4-byte NUID	-
MF1SPLUS8001DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 4 kB EEPROM, 7-byte UID	SOT500-2
MF1SPLUS8011DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 4 kB EEPROM, 4-byte UID	SOT500-2
MF1SPLUS8031DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 4K EEPROM, 4-byte NUID	SOT500-2
MF1SPLUS6001DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format) see Ref. 3, 2 kB EEPROM, 7-byte UID	-
MF1SPLUS6011DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format) see Ref. 3, 2 kB EEPROM, 4-byte UID	-
MF1SPLUS6031DUD/03	FFC	-	8 inch wafer (sawn; 120 µm thickness, on film frame carrier; electronic fail die marking according to SECS-II format), 2K EEPROM, 4byte NUID	-
MF1SPLUS6001DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 2 kB EEPROM, 7-byte UID	SOT500-2
MF1SPLUS6011DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 2 kB EEPROM, 4-byte UID	SOT500-2
MF1SPLUS6031DA4/03	MOA4	PLLMC	plastic leadless module carrier package; 35 mm wide tape, 2K EEPROM, 4-byte NUID	SOT500-2

6. Block diagram

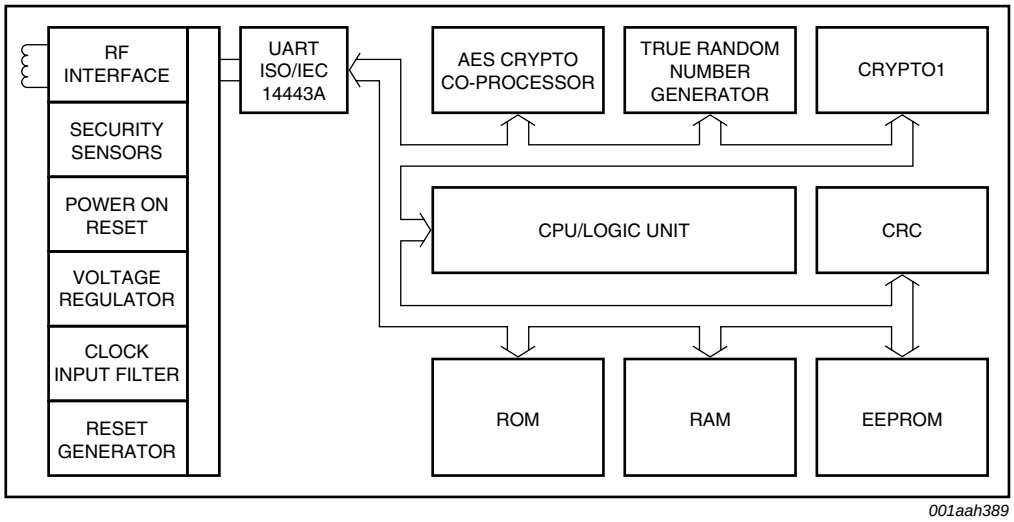

Fig 1. Block diagram

7. Pinning information

7.1 Smart card contactless module

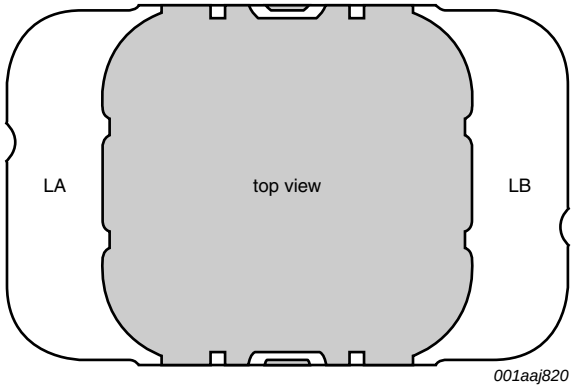

Fig 2. Contact assignments for SOT500-2 (MOA4)

Table 3. Bonding pad assignments to smart card contactless module

Contactless interface module		MF1SPLUSx0y1DA4/z3
Antenna contacts	**Symbol**	**Description**
LA	LA	antenna coil connection LA
LB	LB	antenna coil connection LB

8. Functional description

8.1 Memory organization

The 4 kB EEPROM memory (MF1SPLUS80x) is organized in 32 sectors of 4 blocks and in 8 sectors of 16 blocks. The 2 kB EEPROM memory (MF1SPLUS60x) is organized in 32 sectors of 4 blocks.

One block consists of 16 bytes.

		BYTE NUMBERS WITHIN A BLOCK															
SECTOR	BLOCK	0	1	2	3	4	5(1)	6	7	8	9	10	11	12	13	14	15	DESCRIPTION
39	15	CRYPTO1 key A						access bytes				CRYPTO1 key B or data						sector trailer 39
	14																	data
	13																	data
	...																	...
	...																	...
	2																	data
	1																	data
	0																	data
	...																	...
	...																	...
	...																	...
32	15	CRYPTO1 key A						access bytes				CRYPTO1 key B or data						sector trailer 32
	14																	data
	13																	data
	...																	...
	...																	...
	2																	data
	1																	data
	0																	data
31	3	CRYPTO1 key A						access bytes				CRYPTO1 key B or data						sector trailer 31
	2																	data
	1																	data
	0																	data
	...																	...
	...																	...
	...																	...
0	3	CRYPTO1 key A						access bytes				CRYPTO1 key B or data						sector trailer 0
	2																	data
	1																	data
	0																	manufacturer data

001aaj843

(1) CRYPTO1 Key A in security level 0, 1, 2; plain text access byte in security level 3

Fig 3. Memory organization

8.1.1 Manufacturer block

The first data block (block 0) of the first sector (sector 0) contains the PICC manufacturer data. This block is programmed and write protected at production test.

8.1.2 Data blocks

Sectors 0_D to 31_D contain 3 blocks each and sectors 32_D to 39_D contain 15 blocks for data storage. The data blocks can be configured using the access bits as:

- read/write blocks for storing binary data
- value blocks (only available in security level 1)

Value blocks are special counters where the stored value can be manipulated with specific commands such as MF Increment, MF Decrement and MF Transfer.

These value blocks have a fixed data format enabling error detection and correction with backup management to be performed. Value blocks are only available in security level 1.

A successful mutual authentication is required to allow any data operation.

8.1.2.1 Access conditions

The access conditions for every data block and the sector trailer itself are stored in the sector trailer of the corresponding sector.

The access bits control the rights of memory operations using the secret keys A and B. The access conditions may be altered after authentication with the relevant key and the current access condition allows this operation.

Furthermore, value blocks are configured using the access bits.

8.1.3 AES keys

AES keys are not shown in the memory map. The keys are stored on top of the other data and can be updated and used by referencing the so-called Key Number. In security level 3, anti-tearing is supported for the update of AES keys as well as for the update of the sector trailer. This anti-tearing mechanism is done by the PICC itself. The EEPROM stays in a defined status, even if the PICC is removed from the electromagnetic field during the write operation.

8.1.4 Multi-sector authentication

A new feature has been provided in security level 3 for data which is spread over multiple sectors to improve transaction performance.

Providing that such sectors are secured with identical keys (key value and key type) only one authentication is required to read and/or write data from these sectors. There is no need to re-authenticate when accessing any data within these sectors. Therefore it is possible to configure a card in such a way that operating with only one authentication is needed in security level 3 to access all sectors.

8.1.5 Originality function

The originality function is implemented by an AES authentication with the originality key. The authentication is performed in ISO/IEC 14443-4 protocol layer.

8.2 Card activation and communication protocol

The ISO/IEC 14443-3 anticollision mechanism allows for simultaneous handling of multiple PICCs in the field. The anticollision algorithm selects each PICC individually and ensures that execution of a transaction with a selected PICC is performed correctly without data corruption from other PICCs in the field.

There are three different versions of the PICC. The UID is programmed into a locked part of the NV-memory which is reserved for the manufacturer:

- unique 7-byte serial number
- unique 4-byte serial number
- non-unique 4-byte serial number

Due to security and system requirements, these bytes are write-protected after being programmed by the PICC manufacturer at production.

Remark: The programmed 4-byte NUID serial number is not globally unique which has to be considered in the contactless system design. See Ref. 11 for further information regarding handling of UIDs.

The customer must decide which UID length to use when ordering the product, see Table 2 for ordering information.

During personalization, the PICC can be configured to support Random ID in security level 3. The user can configure whether Random ID or fixed UID shall be used. According to ISO/IEC 14443-3 (see Ref. 5), the first anticollision loop returns the Random Number Tag 08h, the 3-byte Random Number and the BCC, if Random ID is used. The retrieval of the UID in this case can be done using the Virtual Card Support Last command (see Ref. 3) or by reading out block 0.

8.2.1 Backwards compatibility protocol

The backwards compatibility of this product, as used in security level 1 and security level 2, runs on the same protocol layer as MIFARE Classic 1K and MIFARE Classic 4K. The protocol is formed out of the following components:

- Frame definition: according to ISO/IEC 14443-3
- Bit encoding: according to ISO/IEC 14443-2
- Error code handling: handling is proprietary as error codes are formatted in half bytes.
- Command specification: commands are proprietary. Please use the specification as in Ref. 1 and Ref. 2 and the additional commands which are only implemented in MIFARE Plus as described in this document and in Ref. 3.

The following security levels can run on this protocol:

- Security Level 0
- Security Level 1

8.2.2 ISO/IEC 14443-4 Protocol

The ISO/IEC 14443-4 Protocol (also known as T=CL) is used in many processor cards. This protocol is used for the MIFARE Plus with the following security levels:

- Security Level 0: all commands
- Security Level 1: only the security level switch and originality function.
- Security Level 3: all commands

8.3 Security level switching

The MIFARE Plus S offers a unique feature to support migration from CRYPTO1 based systems to AES based operation. The migration on the card-side is done using different security levels supporting different cryptographic algorithms and protocols. There are three security levels:

- Security level 0: initial delivery configuration, used for card personalization
- Security level 1: backwards functional compatibility mode (with MIFARE Classic 1K and MIFARE Classic 4K) with an optional AES authentication
- Security level 3: 3-Pass authentication based on AES, data manipulation commands secured by AES encryption and an AES based MACing method.

The security level switching (i.e. from security level 1 to security level 3) is performed using the dedicated AES authentication switching keys.

The security level can only be switched from a lower level to a higher level, never in the opposite direction.

8.4 Security level 0

Security level 0 is the initial delivery configuration of the PICC. The card can be operated either using the backwards compatibility protocol or the ISO/IEC 14443-4 protocol.

In this level, the card can be personalized including the programming of user data as well as of CRYPTO1 and/or AES keys. In addition, the originality function can be used.

The following mandatory AES keys need to be written using the Write Perso command before the PICC can be switched to security level 1 or security level 3 (for L3 card). Security level switching is performed using the Commit Perso command:

- Card Configuration Key
- Card Master Key
- Level 3 Switch Key

Using the originality function, it is possible to verify that the chip is a genuine NXP Semiconductors MIFARE Plus.

8.5 Security level 1

Security level 1 offers the same functionality as a MIFARE Classic 1K and MIFARE Classic 4K using the backwards compatibility protocol. The MIFARE Classic 1K and MIFARE Classic 4K products are specified in Ref. 1 and Ref. 2.

Furthermore, an optional AES authentication is available in this level without affecting the MIFARE Classic 1K and MIFARE Classic 4K functionality. The authenticity of the card can be proven using strong cryptographic means with this additional functionality.

The timings may differ from the MIFARE Classic 1K and MIFARE Classic 4K products.

Using the originality function, it is possible to verify that the chip is a genuine NXP Semiconductors MIFARE Plus.

8.6 Security level 3

The operation in security level 3 is solely based on the ISO/IEC 14443-4 protocol layer. The usage of the backwards compatibility protocol is not possible.

In security level 3, a mandatory AES authentication between PICC and reader is conducted, where two keys are generated as a function of the random numbers from the PICC and the reader as well as of the shared key. These two session keys are used to secure the data which is exchanged on the interface between the card and reader. One of the two keys is used to ensure the confidentiality of the command and the response while the other key ensures the integrity of the command and the response.

All commands carry a MAC, such that the PICC will only accept commands from the reader with which it is authenticated. Tampering of operands and messages is detected by checking the MAC. Also all responses contain a MAC, so that the reader on each response knows that neither the command nor the response has been tampered with.

Each response carries a MAC. When the appropriate MAC is received, due to linking of MACs, the reader knows that the command and commands before it was properly executed.

All commands between two consecutive first authenticate commands belong to one transaction and the MACing mechanism assures integrity of the whole transaction.

9. Look-up tables

9.1 Security level 0, 1, 3: ISO/IEC 14443-3

Table 4. ISO/IEC 14443-3

Command	Description
REQA	the REQA and ATQA commands are fully implemented according to ISO/IEC 14443-3.
WUPA	the WAKE-UP command is fully implemented according to ISO/IEC 14443-3.
ANTICOLLISION/SELECT cascade level 1	the ANTICOLLISION and SELECT commands are fully implemented according to ISO/IEC 14443-3. The response is part 1 of the UID.
ANTICOLLISION/SELECT cascade level 2 for 7 byte UID version	the ANTICOLLISION and SELECT commands are fully implemented according to ISO/IEC 14443-3. The response is part 2 of the UID.
HALT	the HALT command is fully implemented according to ISO/IEC 14443-3

9.2 Security level 0, 1, 3: ISO/IEC 14443-4

Table 5. ISO/IEC 14443-4

Command	Description
RATS	the response to the RATS command identifies the PICC type to the PCD.
PPS	the PPS command allows an individual selection of the communication baud rate between PCD and PICC. It is possible for the MF1SPLUSx0y1 to individually set the communication baud rate independently of each other for both directions i.e. MF1SPLUSx0y1 allows a non-symmetrical information interchange speed.
DESELECT	deselection according to ISO/IEC 14443-4

Please find more information on ISO/IEC 14443 in Ref. 5 as well as on the settings of ATQA, SAK and ATS in Ref. 4.

9.3 Security level 0 command overview

Table 6. Security level 0 command overview

Command	Description
Write Perso	pre-personalization of AES keys and all blocks
Commit Perso	switch to security level 1
First Authenticate (part 1)	first authenticate
Following Authenticate (part 1)	following authenticate
Authenticate (part 2)	second authentication step

9.4 Security level 1 command overview

Table 7. Security level 1 command overview

MF1ICS50, MF1ICS70, MF1ICS20 commands	Description
MF Authenticate key A	authentication with key A
MF Authenticate key B	authentication with key B
MF Read	reading data
MF Write	writing data
MF Increment	incrementing a value
MF Decrement	decrementing a value
MF Restore	restoring a value
MF Transfer	transferring a value
Commands using backwards compatibility protocol, see Section 8.2.1	
Following Authenticate (part 1)	following authenticate; protocol used as described in Section 8.2.1
Authenticate (part 2)	second authentication step; protocol used as described in Section 8.2.1

Table 7. Security level 1 command overview *...continued*

MF1ICS50, MF1ICS70, MF1ICS20 commands	Description
Command set for security level switch and originality function using ISO/IEC 14443-4 protocol	
First Authenticate (part 1)	first authenticate
Following Authenticate (part 1)	following authenticate
Authenticate (part 2)	second authentication step

9.5 Security level 3 command overview

Table 8. Security level 3 command overview

Command	Description
MIFARE Plus commands	
First Authenticate (part 1)	first authenticate
Following Authenticate (part 1)	following authenticate
Authenticate (part 2)	second authentication step
ResetAuth	reset the authentication step
READ commands	
Read Plain MACed	reading in plain, MAC on response, MAC on command
WRITE commands	
Write MACed	writing encrypted, MAC on response, MAC on command
Write Plain MACed	writing in plain, MAC on response, MAC on command
Virtual card concept	
Virtual Card Support Last	check if the virtual card concept is supported, communicate PCD capabilities and retrieve the UID
Deselect Virtual Card	deselect the virtual card

10. Limiting values

Table 9. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max[1][2]	Unit
I_I	input current		-	30	mA
P_{tot}/pack	total power dissipation per package		-	200	mW
T_{stg}	storage temperature		−55	125	°C
T_{amb}	ambient temperature		−25	70	°C
V_{ESD}	electrostatic discharge voltage	[3]	2	-	kV
I_{lu}	latch-up current		±100	-	mA

[1] Stresses above one or more of the limiting values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] MIL Standard 883-C method 3015; Human body model: C = 100 pF, R = 1.5 kΩ.

11. Abbreviations

Table 10. Abbreviations and symbols

Acronym	Description
AES	Advanced Encryption Standard
EEPROM	Electrically Erasable Programmable Read-Only Memory
LCR	L = inductance, Capacitance, Resistance (LCR meter)
MAC	Message Authentication Code
NUID	Non-Unique IDentifier
NV	Non-Volatile memory
PCD	Proximity Coupling Device (Contactless Reader)
PICC	Proximity Integrated Circuit Card (Contactless Card)
PPS	Protocol Parameter Selection
RATS	Request Answer To Select
REQA	REQuest Answer
SAK	Select AcKnowledge, type A
SECS-II	SEMI Equipment Communications Standard part 2
UID	Unique IDentifier
VC	Virtual Card, one MIFARE Plus PICC is one virtual card
WUPA	Wake-Up Protocol type A

12. References

[1] **Data sheet — MF1ICS50 Functional specification, BU-ID Doc. No. 0010****[2].

[2] **Data sheet — MF1ICS70 Functional specification, BU-ID Doc. No. 0435****.

[3] **Data sheet — M1PLUSx0y1 MIFARE Plus functional specification, BU-ID Doc. No. 1637****.

[4] **Application note —** MIFARE Type identification procedure, BU-ID Doc. No. 1843****.

[5] **Application note —** ISO 14443 PICC selection, BU-ID Doc. No. 1308****.

[6] **NIST Special Publication 800-38A —** Recommendation for block cipher modes of operation: methods and techniques, 2001.

[7] **NIST Special Publication 800-38B —** Recommendation for block cipher modes of operation: The CMAC mode for authentication.

[8] **ISO/IEC Standard —** ISO/IEC 14443 Identification cards - contactless integrated circuit cards - proximity cards.

[9] **FIPS PUB 197 ADVANCED ENCRYPTION STANDARD —** Recommendation for block cipher modes of operation: Methods and techniques.

[10] **ISO/IEC Standard —** ISO/IEC 9797-1 Information technology - security techniques - Message Authentication Codes (MACs) - Part 1: Mechanisms using a block cipher.

[11] **MIFARE and handling of UIDs —** Application note, BU-ID Document number 1907****[2]

2. ** ... document version number

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF1SPLUSX0Y1_SDS v.3.2	20110221	Product short data sheet	-	MF1SPLUSX0Y1_SDS_31
Modifications:	• Added description and ordering information for NUID Types in Section 2, Section 5 and Section 8.2.			
MF1SPLUSX0Y1_SDS_31	20100419	Product short data sheet	-	187030
Modifications:	• Minor text and standardization modifications.			
187030	20100211	Product short data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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15. Contact information

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16. Tables

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Date of release: 21 February 2011
187032

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
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- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

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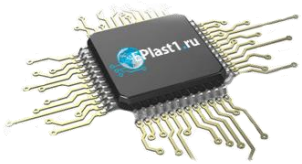
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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